Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-12-02
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to " Supplier Comment" section	Representative Email *	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

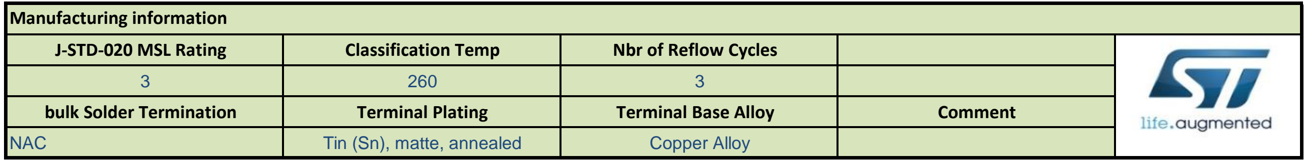
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STA8088FG	A0EG*V765BBQ	B	ZU1A	2013-12-02
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	155.06	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
BGA	7x7x1.0	56	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList :REACH-20th June 2013				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						**Mfr Item Name**	**A0EG*V765BBQ**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Silicon Die	Other inorganic materials	8.100	mg	Supplier	Silicon die	Silicon (Si)	7440-21-3		8.037	mg	992222	51831
Silicon Die				Supplier	die metallization	Alumimium (Al)	7429-90-5		0.003	mg	370	19
Silicon Die				Supplier	die metallization	Copper (Cu)	7440-50-8		0.009	mg	1111	58
Silicon Die				Supplier	die metallization	Tantalum (Ta)	7440-25-7		0.017	mg	2099	110
Silicon Die				Supplier	coating	Gamma-butyrolactone	96-48-0		0.023	mg	2840	148
Silicon Die				Supplier	coating	Polyhydroxyamide	55295-98-2		0.010	mg	1235	64
Silicon Die				Supplier	coating	Alcoxysilane	na		0.001	mg	123	6
Leadframe	Other inorganic materials	99.400	mg	Supplier	alloy	Copper (Cu)	7440-50-8		95.823	mg	964014	617966
Leadframe				Supplier	alloy	Iron (Fe)	7439-89-6		2.310	mg	23239	14897
Leadframe				Supplier	alloy	Phosphorous (P)	7723-14-0		0.029	mg	292	187
Leadframe				Supplier	alloy	Zinc (Zn)	7440-66-6		0.118	mg	1187	761
Leadframe				Supplier	coating	Silver (Ag)	7440-22-4		1.120	mg	11268	7223
Die Attach	Other inorganic materials	1.521	mg	Supplier	glue	Silver (Ag)	7440-22-4		1.146	mg	753452	7391
Die Attach				Supplier	glue	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.081	mg	53254	522
Die Attach				Supplier	glue	Other Epoxy resins	Trade secret		0.075	mg	49310	484
Die Attach				Supplier	glue	P-Terbutylphenyl glycidyl ether	3101-60-8		0.040	mg	26298	258
Die Attach				Supplier	glue	1-cyanoguanidine	461-58-5		0.005	mg	3287	32
Bonding wire	Other inorganic materials	0.250	mg	Supplier	Bonding wire	Gold (Au)	7440-57-5		0.248	mg	990000	1596
Bonding wire				Supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.003	mg	10000	16
Encapsulation	Other inorganic materials	41.271	mg	Supplier	resin	Epoxy resins	Trade secret		3.302	mg	80008	21295
Encapsulation				Supplier	resin	Phenol resin	Trade secret		2.064	mg	50011	13311
Encapsulation				Supplier	resin	Carbon Black	1333-86-4		0.124	mg	3005	800
Encapsulation				Supplier	resin	Silica, vitreous	60676-86-0		35.781	mg	866977	230753
Connection Coating	Other inorganic materials	4.520	mg	Supplier	solder	Tin (Sn)	7440-31-5		4.520	mg	1000000	29150